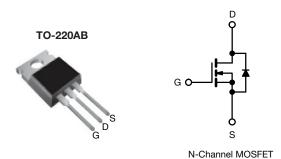


Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	800				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	6.5			
Q _g max. (nC)	38				
Q _{gs} (nC)	5.0				
Q _{gd} (nC)	21				
Configuration	Single				

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	IRFBE20PbF			
Lead (Pb)-free and halogen-free	IRFBE20PbF-BE3			

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, um	ess offici wis				
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	800	V	
Gate-source voltage			V _{GS}	± 20	7 v	
Continuous drain current	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		1.8	А	
	V _{GS} at 10 V	T _C = 100 °C	I _D	1.2		
Pulsed drain current ^a			I _{DM}	7.2	1	
Linear derating factor				0.43	W/°C	
Single pulse avalanche energy ^b			E _{AS}	180	mJ	
Repetitive avalanche current a			I _{AR}	1.8	А	
Repetitive avalanche energy ^a			E _{AR}	5.4	mJ	
Maximum power dissipation $T_C = 25 ^{\circ}C$			P _D	54	W	
Peak diode recovery dV/dt ^c			dV/dt	2.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d For 10 s				300		
Manustina taurus	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 104 mH, R_g = 25 Ω , I_{AS} = 1.8 A (see fig. 12)
- c. $I_{SD} \le 1.8$ A, $dI/dt \le 80$ A/ μ s, $V_{DD} \le 600$, $T_{J} \le 150$ °C
- d. 1.6 mm from case

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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJA}	-	62			
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W		
Maximum junction-to-case (drain)	R _{thJC}	-	2.3			

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.98	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	/ _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I _{GSS}	Vo	V _{GS} = ± 20 V		-	± 100	nA
Zava cata valtaca drain augrent	,	$V_{DS} = 8$	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$		-	100	μА
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 640 \text{ V}, \text{ V}$	V _{DS} = 640 V, V _{GS} = 0 V, T _J = 125 °C		-	500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1.1 A ^b	-	-	6.5	Ω
Forward transconductance	9 _{fs}	V _{DS} = 10	00 V, I _D = 1.1 A b	0.80	-	-	S
Dynamic							
Input capacitance	C _{iss}	\	$V_{GS} = 0 V$,		530	-	
Output capacitance	C _{oss}	V	_{DS} = 25 V,	-	150	-	рF
Reverse transfer capacitance	C _{rss}	f = 1.0	f = 1.0 MHz, see fig. 5		90	-	
Total gate charge	Qg			-	-	38	nC
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 1.8 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b	-	-	5.0	
Gate-drain charge	Q _{gd}		See lig. 6 and 16	-	-	21	
Turn-on delay time	t _{d(on)}		1		8.2	-	- ns
Rise time	t _r	$V_{DD} = 400 \text{ V}, I_D = 1.8 \text{ A},$ $R_g = 18 \ \Omega, R_D = 230 \ \Omega, \text{ see fig. } 10^{\text{ b}}$		-	17	-	
Turn-off delay time	t _{d(off)}			-	58	-	
Fall time	t _f			-	27	-	
Gate input resistance	R _g	f = 1 MHz, open drain		0.6	-	4.2	Ω
Internal drain inductance	L _D	6 mm (0.25")	Between lead, 6 mm (0.25") from package and center of die contact		4.5	-	-11
Internal source inductance	L _S				7.5	-	- nH
Drain-Source Body Diode Characteristic	cs					•	
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.8	
Pulsed diode forward current ^a	I _{SM}			-	-	7.2	A
Body diode voltage	V_{SD}	T _J = 25 °C, I ₅	$T_J = 25 ^{\circ}\text{C}, I_S = 1.8 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	1.4	V
Body diode reverse recovery time	t _{rr}	T 05 00 1	4 0 0 41/4± 400 0/ - b	-	380	570	ns
Body diode reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 1.8 \text{A}, \text{dI/dt} = 100 \text{A/}\mu\text{s}^{\text{b}}$		-	0.94	1.4	μC
Forward turn-on time	t _{on}	Intrinsic turn	-on time is negligible (turn	-on is do	minated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

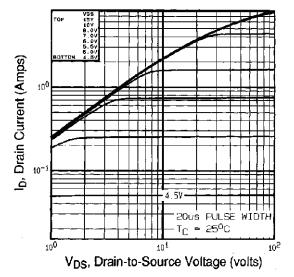


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

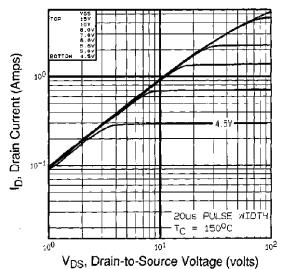


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

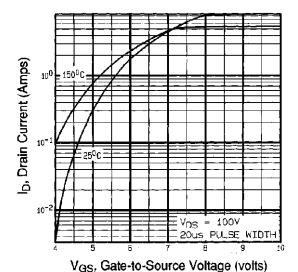


Fig. 3 - Typical Transfer Characteristics

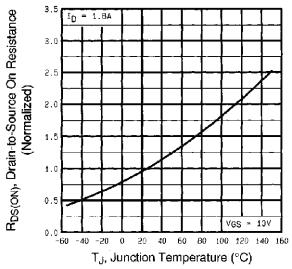


Fig. 4 - Normalized On-Resistance vs. Temperature



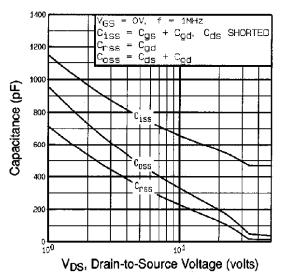


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

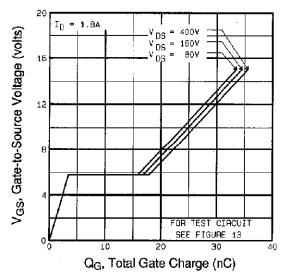


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

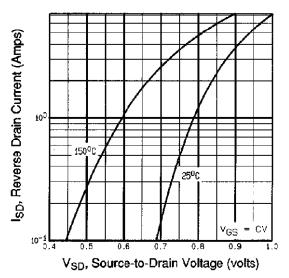


Fig. 7 - Typical Source-Drain Diode Forward Voltage

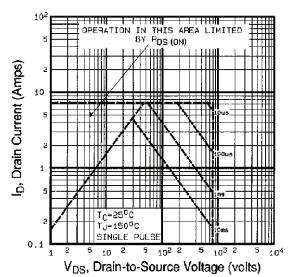


Fig. 8 - Maximum Safe Operating Area



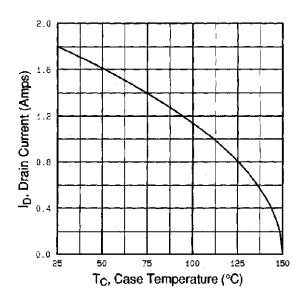


Fig. 9 - Maximum Drain Current vs. Case Temperature

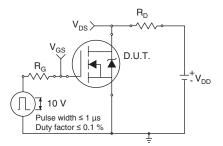


Fig. 10a - Switching Time Test Circuit

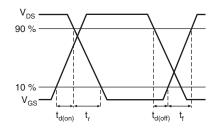


Fig. 10b - Switching Time Waveforms

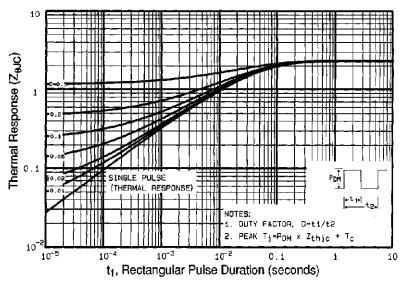


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

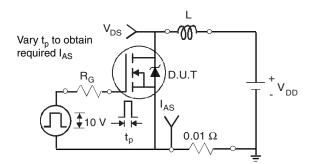


Fig. 12a - Unclamped Inductive Test Circuit

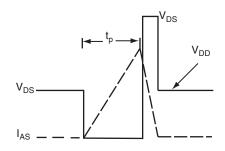


Fig. 12b - Unclamped Inductive Waveforms



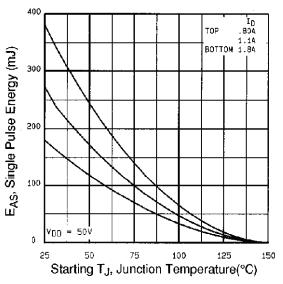


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

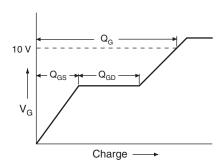


Fig. 13a - Basic Gate Charge Waveform

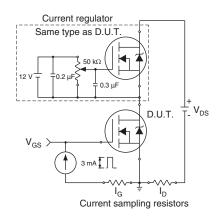
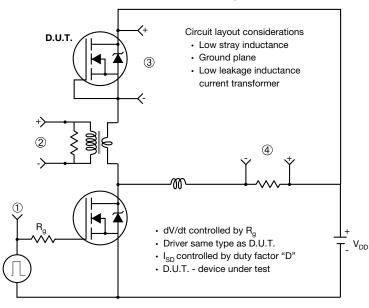


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



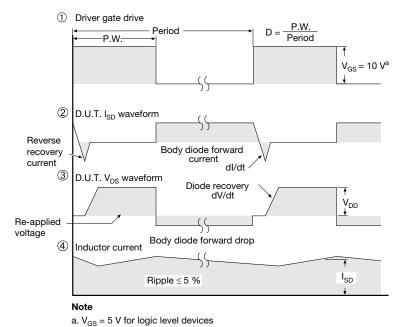
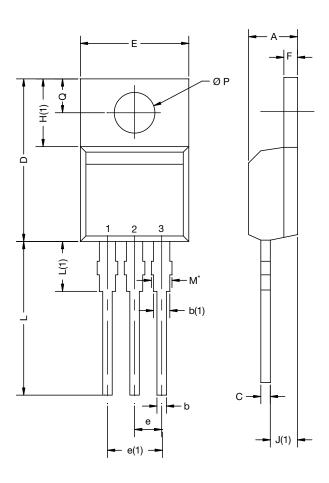


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	METERS	INC	HES		
	MIN.	MAX.	MIN.	MAX.		
A	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
Е	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: E21-0621-Rev. D, 04-Nov-2021 DWG: 6031						

Note

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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